

	Ty pe	L #	Hi ts	Search Text	DBs	Time Stamp	Comme nts	Error Defini tion	Erro rs
1	BRL S	1	0	(substrate with dummy) and (one near2 by near2 one)	USPAT; EPO; JPO	2004/ 08/23 09:31			0
2	BRL S	2	0	(wafer with dummy) and (one near2 by near2 one)	USPAT; EPO; JPO	2004/ 08/23 09:31			0
3	BRL S	3	6	one near2 by near2 one	USPAT; EPO; JPO	2004/ 08/23 09:34			0
4	BRL S	4	52	("4836905" "4923584" "4643629" "5186718" "3652444" "3981791" "4226897" "4311427" "4313815" "4449885" "4457661" "4534314" "4563240" "4634331" "4705951" "4715764" "4851101" "4836733" "4836905" "4895107" "4902934" "4903937" "4909695" "4911597" "4915564" "4917556" "5007981" "5292393" "5452166" "5504033" "5504347" "5556714" "5651858" "5675461" "4313783" "4318767" "4969790" "4924890" "4936329" "5014217" "5007981" "4138306" "4576698" "5014217" "5351415" "4643629" "4824309" "4951601" "5509771" "5462397" "5685684" "4923584" "5436848").pn.	USPAT; EPO; JPO	2004/ 08/23 10:19			0
5	BRL S	5	1	4 and dummy	USPAT; EPO; JPO	2004/ 08/23 09:37			0

	Ty pe	L #	Hi ts	Search Text	DBs	Time Stamp	Comme nts	Error Defini tion	Erro rs
6	BRL S	6	50 51	((substrate wafer) with dummy)	USPAT; EPO; JPO	2004/ 08/23 09:37			0
7	BRL S	7	10 10	6 and vacuum	USPAT; EPO; JPO	2004/ 08/23 09:37			0
8	BRL S	8	21 9	7 and cassette	USPAT; EPO; JPO	2004/ 08/23 09:38			0
9	BRL S	9	59	8 and (34/\$.ccls. 134/\$.ccls.)	USPAT; EPO; JPO	2004/ 08/23 09:42			0
10	BRL S	10	14 8	8 not kato	USPAT; EPO; JPO	2004/ 08/23 09:55			0
11	BRL S	11	1	5169407.pn.	USPAT; EPO; JPO	2004/ 08/23 09:57			0
12	BRL S	12	28 2	dummy with cassette	USPAT; EPO; JPO	2004/ 08/23 09:58			0
13	BRL S	13	10 2	12 and vacuum	USPAT; EPO; JPO	2004/ 08/23 09:58			0
14	BRL S	14	62	13 and (cassette with table)	USPAT; EPO; JPO	2004/ 08/23 10:06			0
15	BRL S	15	79 5	6 and @py<1991	USPAT; EPO; JPO	2004/ 08/23 10:07			0
16	BRL S	16	19	15 and (dummy with cassette)	USPAT; EPO; JPO	2004/ 08/23 10:18			0
17	BRL S	17	1	4923584.pn.	USPAT; EPO; JPO	2004/ 08/23 10:19			0
18	BRL S	18	33	4 and @py<1991	USPAT; EPO; JPO	2004/ 08/23 10:19			0

	Document ID	Issue Date	Title	Current OR	Current XRef	Inventor
1	US 4966520 A	1990 1030	Method of positioning objects to be measured	414/816	414/754	Yokota, Keiichi et al.
2	US 4943767 A	1990 0724	Automatic wafer position aligning method for wafer prober	324/758	348/87	Yokota, Keiichi
3	US 4848270 A	1989 0718	Method and apparatus for forming thin organic film	118/402	118/425; 427/430.1 ;	Wakayama, Shigeru et al.
4	US 4776744 A	1988 1011	Systems and methods for wafer handling in semiconductor process equipment	414/217	269/254R ; 269/287; 414/416.0 9; 414/806; 414/937; 414/938; 414/940	Stonestreet, Paul et al.
5	US 4759681 A	1988 0726	End station for an ion implantation apparatus	414/416.03	118/500; 118/730; 414/278; 414/404; 414/744.2 ; 414/807	Nogami, Mamoru
6	US 4722659 A	1988 0202	Semiconductor wafer carrier transport apparatus	414/222.01	244/230; 414/403; 414/811; 414/937; 414/940	Hoyt, III, Hazen L. et al.
7	JP 02297925 A	1990 1210	METHOD AND APPARATUS FOR TRANSFER OF WAFER IN VERTICAL CVD DIFFUSING DEVICE AND CONTROLLER			HARADA, YASUHIRO et al.
8	JP 02292825 A	1990 1204	CLEANING PROCESS FOR WAFER PROCESSING SOLUTION		204/164	SHIRAISHI, MASATOSHI
9	JP 02106923 A	1990 0419	HEAT TREATING METHOD FOR SUBSTRATE		29/25.01	TAKANABE, EIICHIRO et al.

	Document ID	Issue Date	Title	Current OR	Current XRef	Inventor
10	JP 01298180 A	1989 1201	PLASMA TREATMENT EQUIPMENT		216/59	YAMAMOTO, NORIAKI et al.
11	JP 62132321 A	1987 0615	DRY ETCHING APPARATUS			KANEKO, KAZUAKI et al.
12	JP 62073631 A	1987 0404	SEMICONDUCTOR MANUFACTURING EQUIPMENT		29/25.01	KOSAKA, HIROSHI et al.
13	JP 62023116 A	1987 0131	WET SEMICONDUCTOR MANUFACTURING EQUIPMENT		34/58	EJIRI, IWAO
14	JP 62020320 A	1987 0128	WAFER PROCESSOR		117/954; 438/FOR. 436	KOIKE, ATSUYOSHI
15	JP 61168934 A	1986 0730	WAFER HANDLING METHOD		29/25.01	NOGAMI, TSUKASA
16	JP 61141122 A	1986 0628	EQUIPMENT FOR MANUFACTURING SEMICONDUCTOR DEVICE		118/724; 257/E21. 135	KATO, HIDEAKI
17	JP 60257135 A	1985 1218	ION IMPLANTING DEVICE		148/DIG. 83	FUJIKURA, YOICHI et al.
18	JP 60113428 A	1985 0619	MANUFACTURING EQUIPMENT OF SEMICONDUCTOR		29/25.01; 257/E21. 214	TAMAI, KENJI et al.
19	EP 381338 A2	1990 0808	Method and apparatus for the transfer of wafers in a vertical cvd diffusion apparatus.		29/25.01	HARADA, YASUHIRO et al.